

SOLDER PASTE

BGA LEAD SOLDER PASTE



Sn63/Pb37

Melting point 183°C



Product Usage



TIN PASTE

Model	BST-506A
Name	Moderate temperature Solder paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	50g
Granule	20~38μm
Size	φ50*16mm

Sn63/Pb37

Lead-containing mid-temperature melting point

183°C





Low residue

Fine grain

Rapid welding

Solder spot bright



Welding requirements for a wide range of products



**SMT
patch**



**LED
patch**



**BGA
welding**

Product Size



G.W.:50g

